



## Surface Mount Ultrafast Rectifier



DO-214AB (SMC)

### FEATURES

- Low profile package
- Ideal for automated placement
- Oxide planar chip junction
- Ultrafast recovery times for high frequency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### TYPICAL APPLICATIONS

For use in secondary rectification, and freewheeling for ultrafast switching speeds of AC/AC and DC/DC converters in high temperature conditions for both consumer and automotive applications.

### MECHANICAL DATA

**Case:** DO-214AB (SMC)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test

**Polarity:** Color band denotes cathode end

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3.0 A
$V_{RRM}$	100 V, 150 V, 200 V
$I_{FSM}$	80 A
$t_{rr}$	25 ns
$V_F$ at $I_F = 3.0$ A	0.75 V
$T_J$ max.	175 °C
Package	DO-214AB (SMC)
Diode variations	Single die

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)					
PARAMETER	SYMBOL	UH3B	UH3C	UH3D	UNIT
Device marking code		HB	HC	HD	
Maximum repetitive peak reverse voltage	$V_{RRM}$	100	150	200	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}^{(1)}$	2.5			A
	$I_{F(AV)}^{(2)}$	3.0			
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	80			A
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +175			°C

#### Notes

(1) Free air, mounted on recommended copper pad area

(2) Units mounted on PCB with 0.31" x 0.31" (8.0 mm x 8.0 mm) copper pad area

ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.5 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.85	-	V
	I <sub>F</sub> = 3.0 A			0.95	1.05	
	I <sub>F</sub> = 1.5 A	T <sub>A</sub> = 125 °C		0.65	-	
	I <sub>F</sub> = 3.0 A			0.75	0.90	
Reverse current	Rated V <sub>R</sub>	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	5	μA
		T <sub>A</sub> = 125 °C		15	100	
Maximum reverse recovery time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 0.25 A	T <sub>A</sub> = 25 °C	t <sub>rr</sub>	14	25	ns
Typical reverse recovery time	I <sub>F</sub> = 1.0 A, dI/dt = 50 A/μs, V <sub>R</sub> = 30 V, I <sub>rr</sub> = 0.1 I <sub>RM</sub>			23	40	
Typical softness factor (t <sub>b</sub> /t <sub>a</sub> )		T <sub>A</sub> = 125 °C	S	0.2	-	
Typical reverse recovery current	I <sub>F</sub> = 3.0 A, dI/dt = 200 A/μs, V <sub>R</sub> = 200 V		I <sub>RM</sub>	5.0	7.0	A
Typical stored charge			Q <sub>rr</sub>	60	-	nC
Typical junction capacitance			4.0 V, 1 MHz	C <sub>J</sub>	42	-

### Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
- (2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	UH3B	UH3C	UH3D	UNIT
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)</sup>	95			°C/W
	R <sub>θJM</sub> <sup>(1)</sup>	12			

### Note

- (1) Free air, mounted on recommended copper pad area. Thermal resistance R<sub>θJA</sub> - junction to ambient, R<sub>θJM</sub> - junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
UH3D-M3/57T	0.236	57T	850	7" diameter plastic tape and reel
UH3D-M3/9AT	0.236	9AT	3500	13" diameter plastic tape and reel

### RATINGS AND CHARACTERISTICS CURVES (T<sub>A</sub> = 25 °C unless otherwise noted)

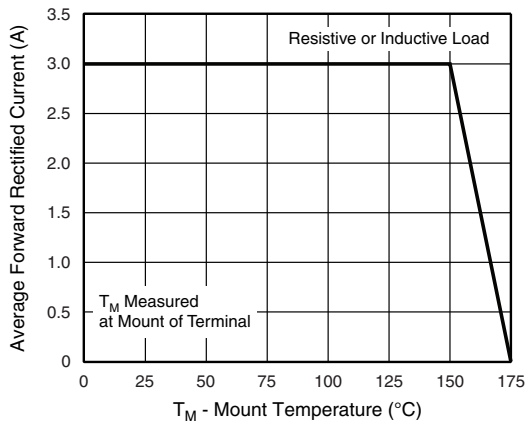


Fig. 1 - Maximum Forward Current Derating Curve

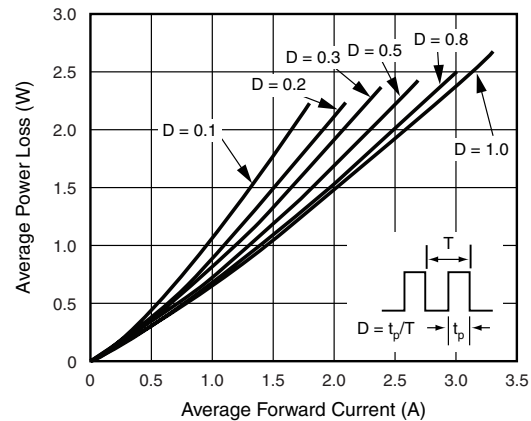


Fig. 2 - Forward Power Loss Characteristics

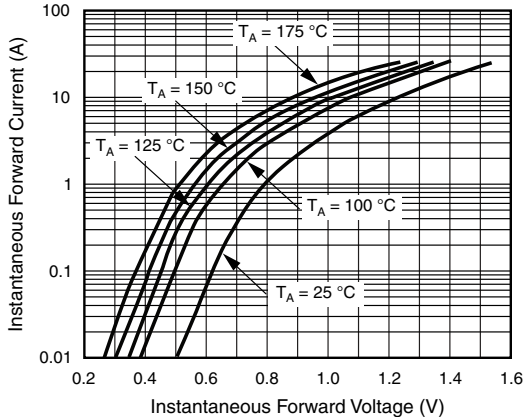


Fig. 3 - Typical Instantaneous Forward Characteristics

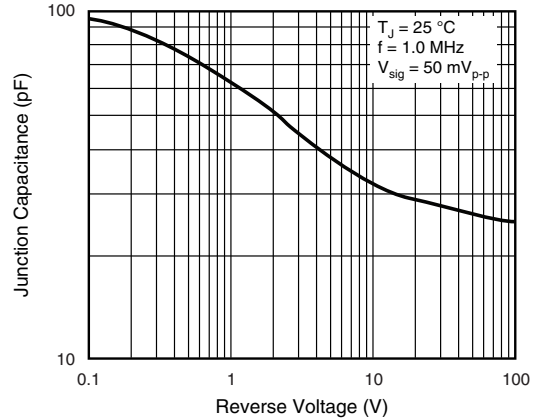


Fig. 5 - Typical Junction Capacitance

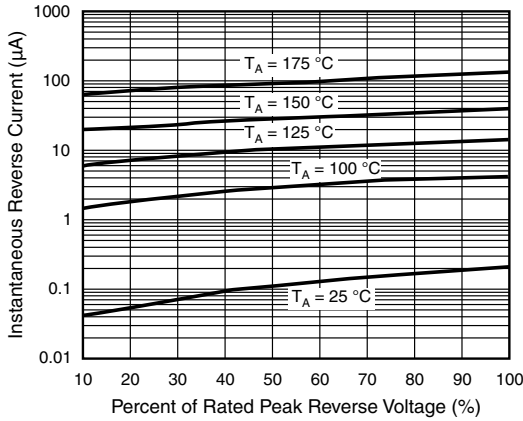


Fig. 4 - Typical Reverse Characteristics

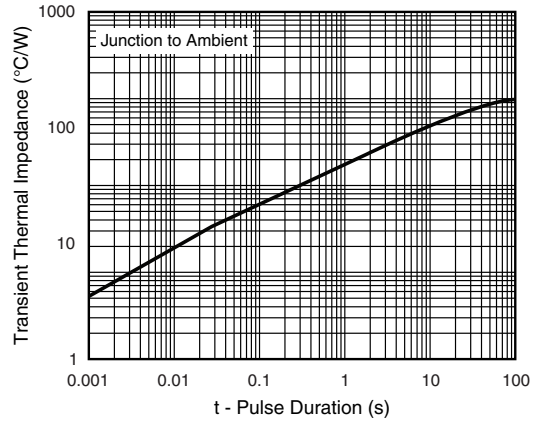
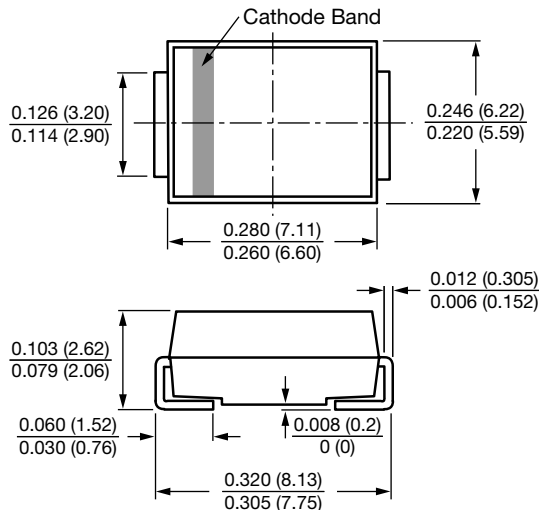


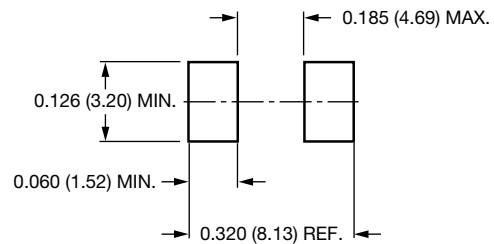
Fig. 6 - Typical Transient Thermal Impedance

## PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

### DO-214AB (SMC)



### Mounting Pad Layout





## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

## Material Category Policy

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**